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<input type="checkbox"/>	L9	L8 and (ammonium hydroxide)	19
<input type="checkbox"/>	L8	L7 and ultrasonic	49
<input type="checkbox"/>	L7	L6 and l3	140
<input type="checkbox"/>	L6	L2 and l1	148
<input type="checkbox"/>	L5	L2 same l1	0
<input type="checkbox"/>	L4	L3 same l2	3558
<input type="checkbox"/>	L3	treating or removing or cleaning or decontaminating	3060975
<input type="checkbox"/>	L2	photomasks	35846
<input type="checkbox"/>	L1	(134/1 or 134/1.3 or 134/2 or 134/3 or 134/25.4 or 134/26 or 134/29).ccls.	9668

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☐ 11. Document ID: US 6681781 B2

L10: Entry 11 of 17

File: USPT

Jan 27, 2004

US-PAT-NO: 6681781

DOCUMENT-IDENTIFIER: US 6681781 B2

**** See image for Certificate of Correction ****TITLE: Methods for cleaning microelectronic substrates using ultradilute cleaning liquids

DATE-ISSUED: January 27, 2004

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Puri; Suraj	Los Altos	CA		
Medeiros, Jr.; Joseph	Santa Clara	CA		
Becker; David Scott	Excelsior	MN		
Narayanswami; Natraj	Eden Prairie	MN		

US-CL-CURRENT: 134/1.3; 134/1, 134/2, 134/21, 134/25.4, 134/32, 134/36, 134/42, 134/902

ABSTRACT:

A method of cleaning a surface of an article using cleaning liquids in combination with acoustic energy. Preferably, an ultradilute concentration of a cleaning enhancement substance, such as ammonia gas, is dissolved in a liquid solvent, such as filtered deionized water, to form a cleaning liquid. The cleaning liquid is caused to contact the surface to be cleaned. Acoustic energy is applied to the liquid during such contact. Optionally, the surface to be cleaned can be oxidized, e.g., by ozonated water, prior to cleaning.

12 Claims, 3 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 3

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	Knowl	Draw D
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☐ 12. Document ID: US 6616773 B1

L10: Entry 12 of 17

File: USPT

Sep 9, 2003

US-PAT-NO: 6616773

DOCUMENT-IDENTIFIER: US 6616773 B1

TITLE: Substrate treatment method

DATE-ISSUED: September 9, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Kuzumoto; Masaki	Tokyo			JP
Noda; Seiji	Tokyo			JP
Oya; Izumi	Tokyo			JP
Miyamoto; Makoto	Tokyo			JP
Horibe; Hideo	Tokyo			JP
Kataoka; Tatsuo	Shizuoka			JP
Oishi; Tetsuji	Shizuoka			JP

US-CL-CURRENT: 134/26; 134/1.3, 134/2, 134/3, 134/31, 134/37, 216/57, 216/83,
216/94

ABSTRACT:

A substrate treatment assembly for treating a work object on a surface of a substrate by supplying to the work object a wet ozone-containing gas wetted with a treatment solution includes a substrate heating device for maintaining a substrate at a temperature higher than room temperature, a wetting device for producing a wet ozone-containing gas by wetting an ozone-containing gas with a treatment solution, a supply device for supplying the wet ozone-containing gas to a work object on a surface of the substrate, a gas conduit connecting the wetting device to the supply device, and a heating device for heating the wet ozone-containing gas to a temperature approximately equal to or greater than the temperature of the substrate.

12 Claims, 36 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 19

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw. Des.
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☐ 13. Document ID: US 6582525 B2

L10: Entry 13 of 17

File: USPT

Jun 24, 2003

US-PAT-NO: 6582525

DOCUMENT-IDENTIFIER: US 6582525 B2

TITLE: Methods for processing a workpiece using steam and ozone

DATE-ISSUED: June 24, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
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Bergman; Eric J. Kalispell MT 59901

US-CL-CURRENT: 134/2; 134/19, 134/25.4, 134/26, 134/28, 134/3, 134/30, 134/31,
134/33, 134/35, 134/36, 134/37, 134/41, 134/902, 257/E21.228, 257/E21.229

ABSTRACT:

In a method for processing a workpiece to remove material from a first surface of the workpiece, steam is introduced onto the first surface under conditions so that at least some of the steam condenses and forms a liquid boundary layer on the first surface. The condensing steam helps to maintain the first surface of the workpiece at an elevated temperature. Ozone is provided around the workpiece under conditions where the ozone diffuses through the boundary layer and reacts with the material on the first surface. The temperature of the first surface is controlled to maintain condensation of the steam.

41 Claims, 7 Drawing figures
Exemplary Claim Number: 1
Number of Drawing Sheets: 7

Full	Title	Citation	Front	Review	Classification	Date	Reference				Claims	KWIC	Draw. Ds
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☐ 14. Document ID: US 6497768 B2

L10: Entry 14 of 17

File: USPT

Dec 24, 2002

US-PAT-NO: 6497768

DOCUMENT-IDENTIFIER: US 6497768 B2

TITLE: Process for treating a workpiece with hydrofluoric acid and ozone

DATE-ISSUED: December 24, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Bergman; Eric J.	Kalispell	MT		

US-CL-CURRENT: 134/3; 134/2, 134/25.4, 134/30, 134/31, 134/33, 134/41, 134/902,
257/E21.228, 257/E21.229

ABSTRACT:

A workpiece or substrate is placed in a support in a reaction chamber. A heated process liquid is sprayed onto the substrate. The thickness of the layer of process liquid formed on the substrate is controlled, e.g., by spinning the substrate. Ozone is introduced into the reaction chamber by injection into the liquid or into the reaction chamber, while the temperature of the substrate is controlled, to chemically process the substrate. The substrate is then rinsed and dried.

28 Claims, 7 Drawing figures
Exemplary Claim Number: 1
Number of Drawing Sheets: 7

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMIC	Drawn De
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☐ 15. Document ID: US 6045621 A

L10: Entry 15 of 17

File: USPT

Apr 4, 2000

US-PAT-NO: 6045621

DOCUMENT-IDENTIFIER: US 6045621 A

TITLE: Method for cleaning objects using a fluid charge

DATE-ISSUED: April 4, 2000

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Puri; Suraj	Los Altos	CA		
Mohindra; Raj	Los Altos Hills	CA		

US-CL-CURRENT: 134/2; 134/10, 134/11, 134/25.4, 134/25.5, 134/26, 134/30, 134/34,
134/36, 134/902, 134/95.1, 134/95.2

ABSTRACT:

A method for cleaning an object. The method (400) includes immersing (420) an object in a liquid comprising water, which can be ultra-clean. The object has a front face, a back face, and an edge. The method includes providing (450) a cleaning enhancement substance (e.g., trace amount of polar organic compound, surfactant, ammonia bearing compound) into the liquid. In one embodiment, the cleaning enhancement substance can form a liquid film, such as a monolayer overlying an upper surface or level of the liquid. The method also includes providing a substantially particle free environment (e.g., ultra-clean gas, ultra-clean non-reactive gas) adjacent to the front face and the back face of the object as the liquid including the cleaning enhancement substance is being removed.

18 Claims, 13 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 9

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMIC	Drawn De
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☐ 16. Document ID: US 5505785 A

L10: Entry 16 of 17

File: USPT

Apr 9, 1996

US-PAT-NO: 5505785

DOCUMENT-IDENTIFIER: US 5505785 A

TITLE: Method and apparatus for cleaning integrated circuit wafers

DATE-ISSUED: April 9, 1996

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Ferrell; Gary W.	Half Moon Bay	CA	94019	

US-CL-CURRENT: 134/1; 134/201, 257/E21.228

ABSTRACT:

A method and apparatus for removing particle, metallic and organic contamination from the wafers used in fabricating integrated circuits is disclosed. In the preferred embodiment, the method comprises the step of placing the wafers to be processed in a vessel or container constructed of a very pure metal, and upon which a surface oxide will quickly form in air. The metal vessel or container is then filled with a cleaning solvent such as sulfuric acid, and are ultrasonically vibrated to remove the contamination. The ultrasonic vibration causes an acoustic streaming of the sulfuric acid, leading to a microflow of the solvent across the surface of the wafer at speeds on the order of several meters per second. This microflow provides for an quick and efficient cleaning of the wafer at reduced temperatures, thereby increasing the overall throughput of the planar fabrication process. The apparatus comprises a vessel or container constructed from a very pure metal, and containing an acidic cleaning solvent. The metal vessel or container is coupled to an ultrasonic vibrating device which ultrasonically vibrates the vessel or container, thereby cleaning the wafers.

21 Claims, 16 Drawing figures

Exemplary Claim Number: 12

Number of Drawing Sheets: 6

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	INDEX	Draw D
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☐ 17. Document ID: US 4239661 A

L10: Entry 17 of 17

File: USPT

Dec 16, 1980

US-PAT-NO: 4239661

DOCUMENT-IDENTIFIER: US 4239661 A

**** See image for Certificate of Correction ****TITLE: Surface-treating agent adapted for intermediate products of a semiconductor device

DATE-ISSUED: December 16, 1980

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Muraoka; Hisashi	Yokohama			JP
Asano; Masafumi	Yokosuka			JP
Ohashi; Taizo	Kanagawa			JP
Shimazaki; Yuza	Tokyo			JP

US-CL-CURRENT: 438/471; 134/2, 134/38, 134/42, 257/E21.228, 430/326, 430/331, 438/329, 438/745, 438/754, 510/175, 510/372, 510/373, 510/421, 510/434, 510/504

ABSTRACT:

A surface-treating agent formed of an aqueous solution containing 0.01 to 20% by weight of trialkyl(hydroxyalkyl) ammonium hydroxide. The treating agent is adapted to be used for the effective removal of organic and inorganic contaminants deposited on the surface of intermediate semiconductor products obtained in the respective steps of manufacturing a semiconductor device and the efficient etching of a metal layer used as wiring. Further, it can be used for the elimination of those portions of a positive working photoresist film coated on the surface of the intermediate semiconductor products which are and are not exposed to a light by controlling its concentration.

32 Claims, 7 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 3

Full	Title	Citation	Front	Review	Classification	Date	Reference				Claims	KWIC	Draw Ds
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Term	Documents
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HYDROGENS	23524
PEROXIDE	252762
PEROXIDES	60386
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(L9 AND (HYDROGEN PEROXIDE)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	17

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☐ 1. Document ID: US 20050133067 A1

L10: Entry 1 of 17

File: PGPB

Jun 23, 2005

PGPUB-DOCUMENT-NUMBER: 20050133067

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20050133067 A1

TITLE: Processing a workpiece using water, a base, and ozone

PUBLICATION-DATE: June 23, 2005

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Bergman, Eric J.	Kalispell	MT	US	

US-CL-CURRENT: 134/26

ABSTRACT:

Contaminants such as photoresist are quickly removed from a wafer having metal features, using water, ozone and a base such as ammonium hydroxide. Processing is performed at room temperature to avoid metal corrosion. Ozone is delivered into a stream of process liquid or into the process environment or chamber. Steam may alternatively be used. A layer of liquid or vapor forms on the wafer surface. The ozone moves through the liquid layer via diffusion, entrainment, jetting/spraying or bulk transfer, and chemically reacts with the photoresist, to remove it.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Draw. Da
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☐ 2. Document ID: US 20040221876 A1

L10: Entry 2 of 17

File: PGPB

Nov 11, 2004

PGPUB-DOCUMENT-NUMBER: 20040221876

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20040221876 A1

TITLE: Method of removing organic materials from substrates

PUBLICATION-DATE: November 11, 2004

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Waleh, Ahmad	Palo Alto	CA	US	
Levenson, Eric O.	Los Altos	CA	US	

US-CL-CURRENT: [134/30](#); [134/1](#), [134/19](#), [134/2](#), [134/26](#), [134/37](#), [134/38](#), [257/E21.229](#)

ABSTRACT:

Water-free, gaseous sulfur trioxide is used as an agent to remove various organic coatings, films, layers and residues from the surface of a substrate when used in conjunction with certain other physical and chemical treatments applied at the appropriate time during the process.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Draw D
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☐ 3. Document ID: US 20040144399 A1

L10: Entry 3 of 17

File: PGPB

Jul 29, 2004

PGPUB-DOCUMENT-NUMBER: 20040144399

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20040144399 A1

TITLE: Processing of semiconductor components with dense processing fluids and ultrasonic energy

PUBLICATION-DATE: July 29, 2004

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
McDermott, Wayne Thomas	Fogelsville	PA	US	
Subawalla, Hoshang	Macungie	PA	US	
Johnson, Andrew David	Doylestown	PA	US	
Schwarz, Alexander	Bethlehem	PA	US	

US-CL-CURRENT: [134/1](#); [134/1.3](#), [134/11](#), [134/198](#), [134/34](#), [134/35](#), [134/37](#)

ABSTRACT:

Method for processing an article with a dense processing fluid in a processing chamber while applying ultrasonic energy during processing. The dense fluid may be generated in a separate pressurization vessel and transferred to the processing chamber, or alternatively may be generated directly in the processing chamber. A processing agent may be added to the pressurization vessel, to the processing chamber, or to the dense fluid during transfer from the pressurization vessel to the processing chamber. The ultrasonic energy may be generated continuously at a constant frequency or at variable frequencies. Alternatively, the ultrasonic energy may be generated intermittently.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Draw D
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☐ 4. Document ID: US 20040055621 A1

L10: Entry 4 of 17

File: PGPB

Mar 25, 2004

PGPUB-DOCUMENT-NUMBER: 20040055621
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20040055621 A1

TITLE: Processing of semiconductor components with dense processing fluids and
ultrasonic energy

PUBLICATION-DATE: March 25, 2004

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
McDermott, Wayne Thomas	Fogelsville	PA	US	
Subawalla, Hoshang	Macungie	PA	US	
Johnson, Andrew David	Doylestown	PA	US	
Schwarz, Alexander	Bethlehem	PA	US	

US-CL-CURRENT: 134/1.3; 134/184, 134/26, 134/34, 134/95.1

ABSTRACT:

Method for processing an article with a dense processing fluid in a processing chamber while applying ultrasonic energy during processing. The dense fluid may be generated in a separate pressurization vessel and transferred to the processing chamber, or alternatively may be generated directly in the processing chamber. A processing agent may be added to the pressurization vessel, to the processing chamber, or to the dense fluid during transfer from the pressurization vessel to the processing chamber. The ultrasonic energy may be generated continuously at a constant frequency or at variable frequencies. Alternatively, the ultrasonic energy may be generated intermittently.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	RISC	Draw Da
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☐ 5. Document ID: US 20030205240 A1

L10: Entry 5 of 17

File: PGPB

Nov 6, 2003

PGPUB-DOCUMENT-NUMBER: 20030205240
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20030205240 A1

TITLE: Apparatus for treating a workpiece with steam and ozone

PUBLICATION-DATE: November 6, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
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Bergman, Eric J. Kalispell MT US

US-CL-CURRENT: [134/3](#); [257/E21.228](#), [257/E21.229](#), [257/E23.054](#)

ABSTRACT:

In a method for processing a workpiece to remove material from a first surface of the workpiece, steam is introduced onto the first surface under conditions so that at least some of the steam condenses and forms a liquid boundary layer on the first surface. The condensing steam helps to maintain the first surface of the workpiece at an elevated temperature. Ozone is provided around the workpiece under conditions where the ozone diffuses through the boundary layer and reacts with the material on the first surface. The temperature of the first surface is controlled to maintain condensation of the steam.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KIMC	Draw De
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☐ 6. Document ID: US 20020050279 A1

L10: Entry 6 of 17

File: PGPB

May 2, 2002

PGPUB-DOCUMENT-NUMBER: 20020050279

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20020050279 A1

TITLE: Process and apparatus for treating a workpiece with hydrofluoric acid and ozone

PUBLICATION-DATE: May 2, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Bergman, Eric J.	Kalispell	MT	US	

US-CL-CURRENT: [134/3](#); [134/19](#), [134/2](#), [134/26](#), [134/28](#), [134/30](#), [134/31](#), [134/32](#), [134/33](#), [134/34](#), [134/35](#), [134/41](#), [257/E21.228](#) , [257/E21.229](#)

ABSTRACT:

A workpiece or substrate is placed in a support in a reaction chamber. A heated process liquid is sprayed onto the substrate. The thickness of the layer of process liquid formed on the substrate is controlled, e.g., by spinning the substrate. Ozone is introduced into the reaction chamber by injection into the liquid or into the reaction chamber, while the temperature of the substrate is controlled, to chemically process the substrate. The substrate is then rinsed and dried.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KIMC	Draw De
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☐ 7. Document ID: US 20020020436 A1

L10: Entry 7 of 17

File: PGPB

Feb 21, 2002

PGPUB-DOCUMENT-NUMBER: 20020020436
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20020020436 A1

TITLE: Process and apparatus for treating a workpiece with steam and ozone

PUBLICATION-DATE: February 21, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Bergman, Eric J.	Kalispell	MT	US	

US-CL-CURRENT: 134/30; 134/19, 134/2, 134/26, 134/28, 134/3, 134/31, 134/35,
134/36, 134/37, 134/41, 134/42, 257/E21.228 , 257/E21.229

ABSTRACT:

In a method for processing a workpiece to remove material from a first surface of the workpiece, steam is introduced onto the first surface under conditions so that at least some of the steam condenses and forms a liquid boundary layer on the first surface. The condensing steam helps to maintain the first surface of the workpiece at an elevated temperature. Ozone is provided around the workpiece under conditions where the ozone diffuses through the boundary layer and reacts with the material on the first surface. The temperature of the first surface is controlled to maintain condensation of the steam.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KMC	Draw D
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☐ 8. Document ID: US 20020011253 A1

L10: Entry 8 of 17

File: PGPB

Jan 31, 2002

PGPUB-DOCUMENT-NUMBER: 20020011253
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20020011253 A1

TITLE: METHODS FOR CLEANING MICROELECTRONIC SUBSTRATES USING ULTRADILUTE CLEANING LIQUIDS

PUBLICATION-DATE: January 31, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Puri, Suraj	Los Altos	CA	US	
Medeiros, Joseph JR.	Santa Clara	CA	US	
Becker, David Scott	Excelsior	MN	US	
Narayanswami, Natraj	Eden Prairie	MN	US	

US-CL-CURRENT: 134/1; 134/1.3, 134/2, 134/21, 134/25.4, 134/32, 134/36, 134/42,

134/902

ABSTRACT:

A method of cleaning a surface of an article using cleaning liquids in combination with acoustic energy. Preferably, an ultradilute concentration of a cleaning enhancement substance, such as ammonia gas, is dissolved in a liquid solvent, such as filtered deionized water, to form a cleaning liquid. The cleaning liquid is caused to contact the surface to be cleaned. Acoustic energy is applied to the liquid during such contact. Optionally, the surface to be cleaned can be oxidized, e.g., by ozonated water, prior to cleaning.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Draw. De
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☐ 9. Document ID: US 6869487 B1

L10: Entry 9 of 17

File: USPT

Mar 22, 2005

US-PAT-NO: 6869487

DOCUMENT-IDENTIFIER: US 6869487 B1

TITLE: Process and apparatus for treating a workpiece such as a semiconductor wafer

DATE-ISSUED: March 22, 2005

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Bergman; Eric J.	Kalispell	MT		

US-CL-CURRENT: 134/3; 134/102.1, 134/102.2, 134/108, 134/111, 134/19, 134/199,
134/2, 134/25.4, 134/26, 134/30, 134/31, 134/33, 134/902

ABSTRACT:

A novel chemistry, system and application technique reduces contamination of semiconductor wafers and similar substrates and enhances and expedites processing. A stream of liquid chemical is applied to the workpiece surface. Ozone is delivered either into the liquid process stream or into the process environment. The ozone is preferably generated by a high capacity ozone generator. The chemical stream is provided in the form of a liquid or vapor. A boundary layer liquid or vapor forms on the workpiece surface. The thickness of the boundary layer is controlled. The chemical stream may include ammonium hydroxide for simultaneous particle and organic removal, another chemical to raise the pH of the solution, or other chemical additives designed to accomplish one or more specific cleaning steps.

25 Claims, 7 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 7

Full	Title	Citation	Front	Review	Classification	Date	Reference				Claims	KWIC	Draw. De
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10. Document ID: US 6841008 B1

L10: Entry 10 of 17

File: USPT

Jan 11, 2005

US-PAT-NO: 6841008

DOCUMENT-IDENTIFIER: US 6841008 B1

TITLE: Method for cleaning plasma etch chamber structures

DATE-ISSUED: January 11, 2005

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Branco; Walter G.	San Jose	CA		
Qiao; Jianmiu	Fremont	CA		

US-CL-CURRENT: 134/26; 134/1.1, 134/30, 438/905

ABSTRACT:

A method for cleaning a plasma reactor clamber part (100) may include dipping the chamber part in a solvent (102) that may dissolve a material that has been redistributed on the chamber part by a reactive plasma. A chamber part may then be rinsed (104), ultrasonically cleaned (106) in a ultrasonic cleaning liquid, and then rinsed again with a liquid that may evaporate at a lower temperature than an ultrasonic cleaning liquid (108). A chamber part may then be blown dry (110) and baked (112). In addition, or alternatively, a method may also include plasma cleaning a chamber part (202).

12 Claims, 5 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 3

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	Index	Draw De
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Term	Documents
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HYDROGENS	23524
PEROXIDE	252762
PEROXIDES	60386
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